IN THE CLAIMS

Please cancel claims 18, 26, and 35 without prejudice.

Please amend claims 17, 21-24, 30, 32, and 33 as follows:

1-16 (Cancelled)

17. (Currently Amended) A method to assemble a substrate for a semiconductor package comprising:

providing a substrate comprising a sheet of core material and a plurality of upper contact traces and upper contact pads on its upper surface, a second plurality of lower conducting traces and external contact areas on its bottom surface and conducting vias connecting the upper conducting traces and lower conducting traces;

forming a plurality of non-plated vent holes ~~in~~through the substrate in ~~an area in which~~ a semiconductor chip ~~will be mounted to~~mounting area defined on the upper surface and in areas of the substrate ~~which will be~~ adjacent to the ~~area in which the~~ semiconductor chip mounting area~~will be mounted~~; and

covering the upper ~~and lower surfaces~~surface of the substrate ~~by~~with a layer of solder resist and the lower surface of the substrate with a layer of solder resist, but leaving the contact areas free from solder resist, wherein the layer of solder resist on the upper surface of the substrate closes one end of the vent holes.

18. (Cancelled)

19. (Previously Presented) The method to assemble a substrate of claim 17, wherein the vent holes include solder resist.

20. (Previously Presented) The method to assemble a substrate of claim 17, wherein the vent holes are formed by drilling.

21. (Currently Amended) The method to assemble a substrate of claim 17, further comprising forming the vent holes in the core material before forming a plurality of upper contact traces and upper contact pads on its upper surface, a second plurality of lower conducting traces and external contact areas on its bottom surface and depositing conducting vias.

22. (Currently Amended) A method to assemble a semiconductor package comprising:

providing a substrate comprising a sheet of core material and a plurality of upper contact traces and upper contact pads on its upper surface, a second plurality of lower conducting traces and external contact areas on its bottom surface and conducting vias connecting the upper conducting traces and lower conducting traces;

forming a plurality of non-plated vent holes in the substrate;

covering the upper surface of the substrate with a layer of solder resist and the lower surfaces of the substrate ~~by~~with a layer of solder resist leaving the contact areas free from solder resist, wherein the layer of solder resist on the upper surface of the substrate closes one end of the vent holes;

providing a semiconductor chip comprising an active surface including a plurality of chip contact areas;

mounting the chip on the upper surface of the ~~redistribution board~~substrate by microscopic solder balls between the chip contacts and upper contact areas, wherein non-plated vent holes of the plurality of non-plated vent holes are ~~distributed~~disposed in an area of the substrate below and ~~adjacent to~~ the semiconductor chip and in areas adjacent to the semiconductor chip;

performing a solder reflow; and

underfilling the area between the chip and the upper surface of the redistribution board with epoxy resin.

23. (Currently Amended) The method of claim 22, including covering the upper surface of the chip and the substrate with a mold material.

24. (Currently Amended) A substrate for a semiconductor package comprising:

a sheet of core material;

a plurality of upper conducting traces and upper contact pads on an upper surface of the sheet, a second plurality of lower conductive traces and external contact areas on a bottom surface of the sheet and a plurality of conducting vias connecting the upper conducting traces and lower conducting traces;

a plurality of non-plated vent holes ~~in~~through the ~~substrate~~sheet in ~~an area in which~~ a semiconductor chip mounting area defined on~~will be mounted to~~ the upper surface and in areas of the substrate ~~which will be~~ adjacent to the ~~area in which the~~ semiconductor chip mounting area~~will be mounted~~; and

a layer of solder resist covering the upper surface of the substrate and a layer of solder resist covering the lower surfaces of the substrate, but leaving the contact areas free from solder resist, wherein the layer of solder resist covering the upper surface closes an end of the vent holes at the upper surface.

25. (Previously Presented) The substrate of claim 24, wherein the vent holes include solder resist.

26. (Cancelled)

27. (Previously Presented) The substrate of claim 24, wherein the plurality of vent holes are laterally located towards the center of the substrate.

28. (Previously Presented) The substrate of claim 24, wherein the plurality of vent holes are laterally located towards the center and towards the outer edges of the substrate.

29. (Previously Presented) The substrate of claim 24, wherein the vent holes have a diameter of approximately 1μm to approximately 5mm or approximately 10μm to approximately 0.5mm or approximately 100μm.

30. (Currently Amended) A semiconductor package comprising:

a sheet of core material;

a plurality of upper conducting traces and upper contact pads on an upper surface of the sheet, a second plurality of lower conductive traces and external contact areas on a bottom surface of the sheet and a plurality of conducting vias connecting the upper conducting traces and lower conducting traces;

a plurality of non-plated vent holes through the sheet;

a layer of solder resist covering the upper ~~and lower~~ surfaces of the sheet and a layer of solder resist covering the lower surface of the sheet but leaving the contact areas free from solder resist, wherein the layer of solder resist covering the upper surface closes an end of the vent holes at the upper surface; and

a semiconductor chip including an active surface with a plurality of chip contact ~~areas,~~areas electrically connected to the sheet, wherein non-plated vent holes of the plurality of non-plated vent holes are ~~distributed~~disposed in an area of the sheet below the semiconductor chip and in areas of the sheet adjacent to the semiconductor chip.

31. (Previously Presented) The semiconductor package of claim 30, wherein the chip is encapsulated by mold material.

32. (Currently Amended) The semiconductor package of claim 30, wherein the chip is mounted to the sheet by ~~the~~a flip-chip technique.

33. (Currently Amended) A substrate for a semiconductor package comprising:

a sheet of core material with an upper surface and a bottom surface each covered with a layer of solder resist;

a plurality of upper conducting traces and upper contact pads on the upper surface;

a plurality of bottom conductive traces and external contact areas on the bottom surface;

a plurality of conducting vias connecting the upper conducting traces and bottom conducting traces;

a plurality of non-plated vent holes through the sheet in a chip mounting area defined on the ~~sheet where a semiconductor chip will be mounted to the~~ upper surface and in areas adjacent to the chip mounting area; and

a layer of solder resist covering the upper surface and a layer of solder resist covering the bottom surfaces except for the contact areas, wherein the layer of solder resist covering the upper surface closes an end of the vent holes at the upper surface.

34. (Previously Presented) The substrate of claim 33, wherein the vent holes include solder resist.

35. (Cancelled)

36. (Previously Presented) The substrate of claim 33, wherein the plurality of vent holes are laterally located towards the center of the substrate.